

Power Electronics Materials

NC-SMQ75 Solder Paste

Industry-proven no-clean "Power-Safe" die-attach paste for high-Pb alloys

- Ultra-low post-reflow residue bonds strongly to overmolding materials
- Finished devices proven to AEC-Q101
- Eliminates cost of cleaning

Solder Preforms and Ribbons

Wide portfolio to meet all needs

- Over 800 solder alloys available
- Tight tolerance gives precise solder volume
- Standard and custom shapes and thicknesses
- Uniformly flux-coated preforms also available

Low-Alpha Solder Paste

- Alpha particle emissions <0.01cph.cm²
- Reduce power MOSFET sub-threshold leakage current

Indium3.2HF Solder Paste with Indalloy®121

Industry-proven water-soluble solder paste for heat spreader attach

- High thermal conductivity
- Low-voiding
- Long working life
- Easy residue cleaning with DI water

QuickSinter®

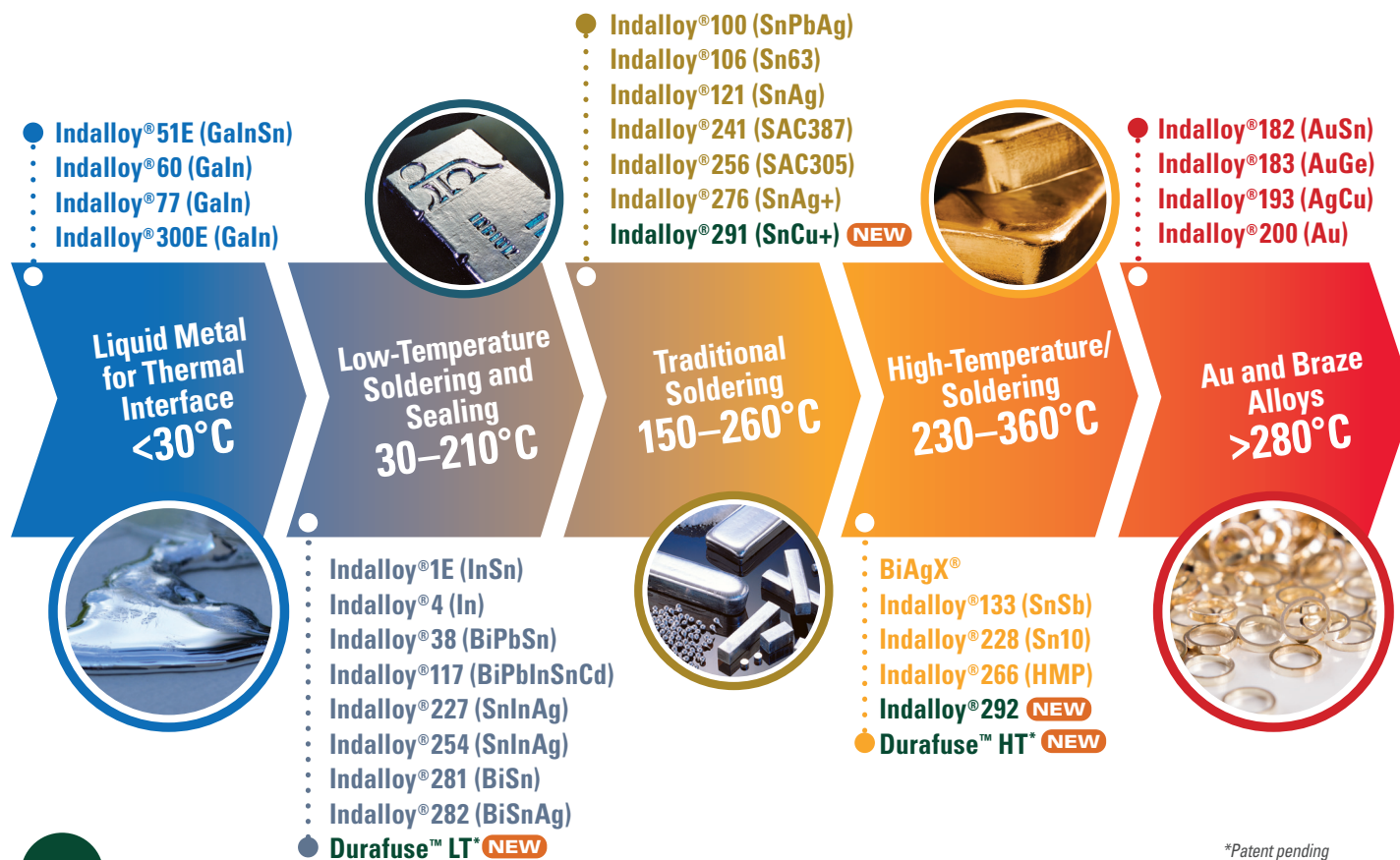
Silver Sintering Paste

- Formulations available for pressure-less and pressure-assisted sintering applications
- Excellent joint strength
- Controllable bondline thickness from 30–70µm
- Versatile sintering profiles

Solutions for Power Electronics

Indium Corporation is the leader in power electronics assembly materials.

Continuous Alloy Innovation



Learn more: www.indium.com/PowerElectronics

Contact our engineers: europe@indium.com

From One Engineer To Another®

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified. Indium Corporation is an ISO 9001:2015 registered company.

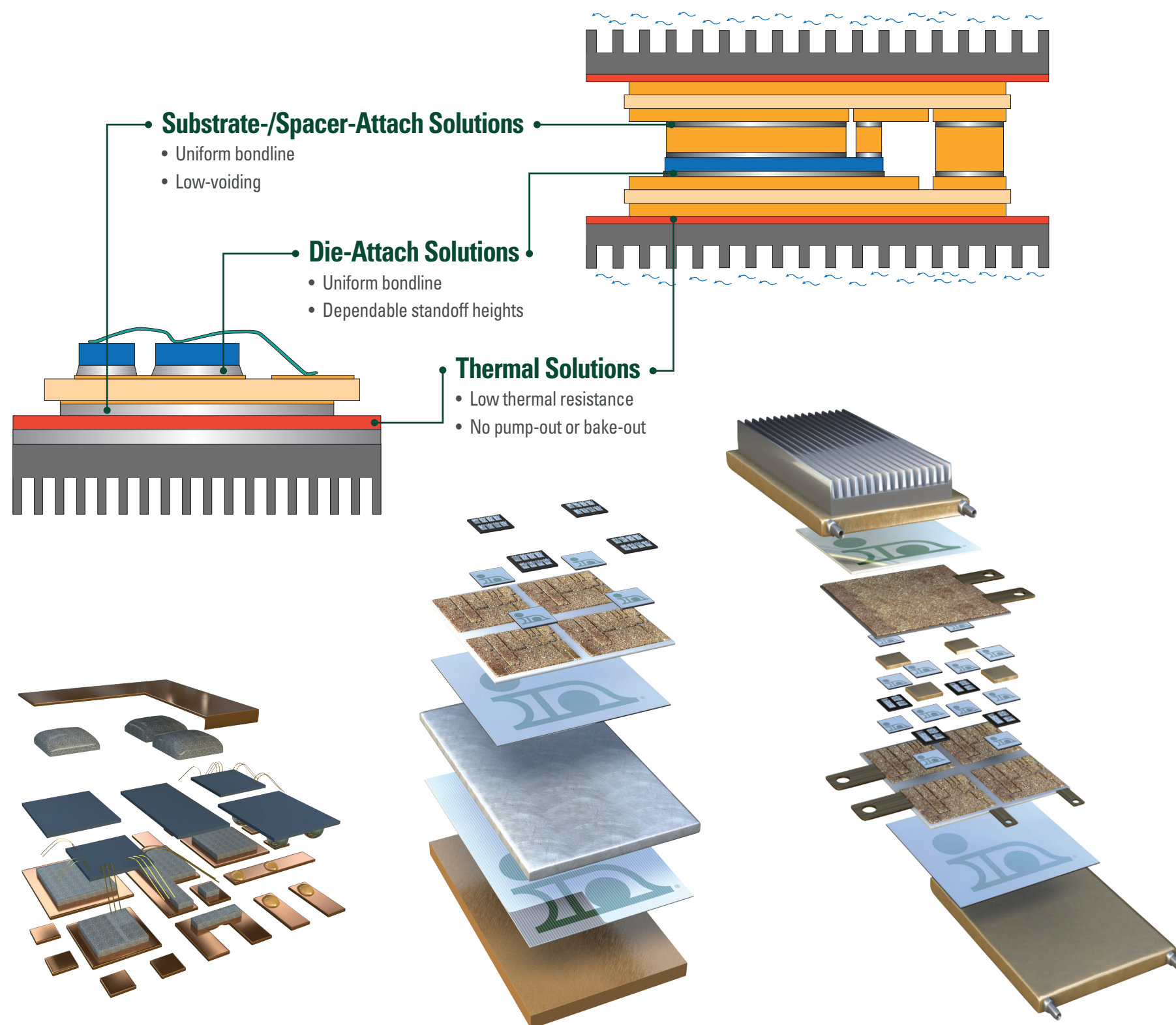
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Form No. 99659 (A4) R2



Solder Redefined™

Solder and Thermal Solutions for ALL Power Electronics Devices



Recommended products for power electronics

InFORMS®

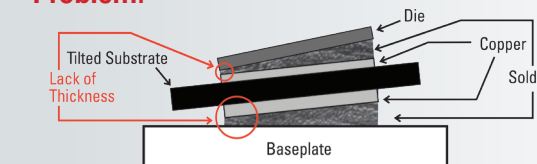
Reinforced Solder Preforms and Ribbon*

Produce consistent bondline thickness on die- and substrate-level

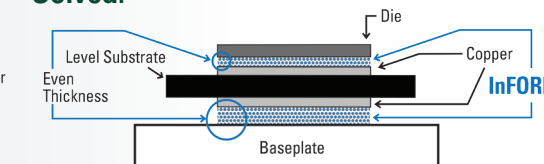
- >2X increase in reliability (-55/+150°C) passes 3,500 thermal cycles
- Most uniform bondline control
- Improved strength and dependable standoff heights

*Patent pending

Problem:



Solved:



Durafuse™ HT

High-Temperature Lead-Free Paste

- Designed to replace high-lead in power discrete applications
- Outperforms high-lead in RDS(on) resistance and thermal cycling

*Patent pending

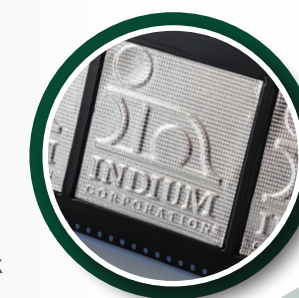


Heat-Spring®

Metal Thermal Interface Materials (Sn+)

Prevent the power die from overheating

- Patterned, compressible interface
- Optimizes performance between the heat source and a heat-sink
- No pump-out or bake-out over time



Low-Power Density

High-Power Density

